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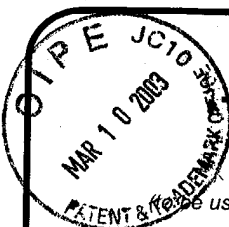


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PTO/SB21 (08-00)

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TRANSMITTAL FORM

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Application Number	10/081,565
Filing Date	February 22, 2002
First Named Inventor	Eliezer Pasternak et al.
Group Art Unit	3729
Examiner Name	Ishwarbhai B. Patel

Total Number of Pages in This Submission

23

Attorney Docket Number 2100259-991141

ENCLOSURES (check all that apply)

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<input type="checkbox"/> Status Letter
<input checked="" type="checkbox"/> Additional Enclosure(s) (please identify below):
Response to Office Action with Attachment A and B (12 pgs.);
Supplemental Declaration (4 pgs.);
Transmittal of Formal Drawings (1 pg);
Four (4) sheets formal drawings;
Certificate of First Class Mailing (1 pg);
Return postcard. |
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Kieun Jenny Sung

Date

March 4, 2003

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Eliezer Pasternak

Serial No.: 10/081,565

Group Art Unit: 2827

Filed: February 22, 2002

Examiner: Ishwarbhai B. Patel

Title: HIGH FREQUENCY DEVICE PACKAGES AND METHODS

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Cathy Pittman

RESPONSE TO OFFICE ACTION

Commissioner for Patents and Trademarks
Washington, DC 20231

Dear Sir/Madam:

In response to the December 4, 2002 Office Action, Applicant requests that the Examiner consider the following remarks and amendments.

IN THE SPECIFICATION

In accordance with 37 C.F.R. 1.121(B)(1), Attachment A contains the marked up version indicating all the changes made.

Please replace the paragraph starting at page 4, line 17 with the following paragraph:

The invention is particularly applicable to microwave device packaging and it is in this context that the invention will be described. It will be appreciated, however, that the high frequency device package and packing method in accordance with the invention has greater utility since it can be used to package any device that operates at high frequencies or any device in which matched impedance vias and bonding wires are desirable.

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